

LM2621 Low Input Voltage, Step-Up DC-DC Converter

1 Features

- Small VSSOP8 Package (Half the Footprint of Standard 8-Pin SOIC Package)
- 1.09-mm Package Height
- Up to 2-MHz Switching Frequency
- 1.2-V to 14-V Input Voltage
- 1.24-V to 14-V Adjustable Output Voltage
- Up to 1A Load Current
- 0.17- Ω Internal MOSFET
- Up to 90% Regulator Efficiency
- 80- μ A Typical Operating Current
- < 2.5- μ A Specified Supply Current In Shutdown

2 Applications

- PDAs, Cellular Phones
- 2-Cell and 3-Cell Battery-Operated Equipment
- PCMCIA Cards, Memory Cards
- Flash Memory Programming
- TFT/LCD Applications
- 3.3-V to 5.0-V Conversion
- GPS Devices
- Two-Way Pagers
- Palmtop Computers
- Hand-Held Instruments

3 Description

The LM2621 is a high efficiency, step-up DC-DC switching regulator for battery-powered and low input voltage systems. It accepts an input voltage between 1.2 V and 14 V and converts it into a regulated output voltage. The output voltage can be adjusted between 1.24 V and 14 V. It has an internal 0.17- Ω N-Channel MOSFET power switch. Efficiencies up to 90% are achievable using the LM2621.

The high switching frequency (adjustable up to 2 MHz) of the LM2621 allows for tiny surface mount inductors and capacitors. Because of the unique constant-duty-cycle gated oscillator topology very high efficiencies are realized over a wide load range. The supply current is reduced to 80 μ A because of the BiCMOS process technology. In the shutdown mode, the supply current is less than 2.5 μ A.

The LM2621 is available in a VSSOP-8 package. This package uses half the board area of a standard 8-pin SOIC and has a height of just 1.09 mm.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM2621	VSSOP (8)	3.00 mm x 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Typical Application Circuit

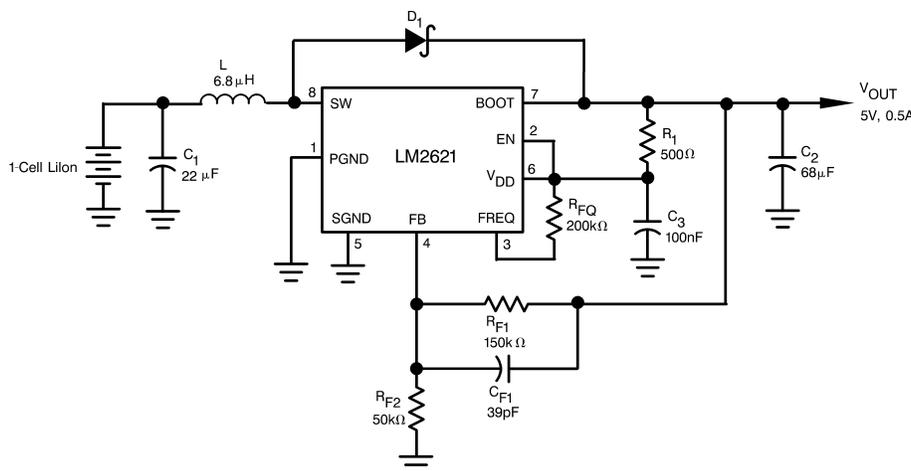


Table of Contents

1 Features	1	8 Application and Implementation	10
2 Applications	1	8.1 Application Information.....	10
3 Description	1	8.2 Typical Applications	10
4 Revision History	2	9 Power Supply Recommendations	15
5 Pin Configuration and Functions	3	10 Layout	15
6 Specifications	3	10.1 Layout Guidelines	15
6.1 Absolute Maximum Ratings	3	10.2 Layout Example	15
6.2 Recommended Operating Conditions.....	4	11 Device and Documentation Support	16
6.3 Thermal Information	4	11.1 Device Support.....	16
6.4 Electrical Characteristics.....	4	11.2 Documentation Support	16
6.5 Typical Characteristics	5	11.3 Community Resources.....	16
7 Detailed Description	8	11.4 Trademarks	16
7.1 Overview	8	11.5 Electrostatic Discharge Caution.....	16
7.2 Functional Block Diagram	8	11.6 Glossary	16
7.3 Feature Description.....	8	12 Mechanical, Packaging, and Orderable	
7.4 Device Functional Modes.....	9	Information	16

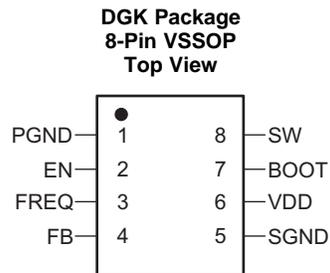
4 Revision History

Changes from Revision C (November 2012) to Revision D

Page

<ul style="list-style-type: none"> Added <i>Pin Configuration and Functions</i> section, <i>Handling Rating</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section 	1
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5 Pin Configuration and Functions



Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
PGND	1	GND	Power Ground
EN	2	I	Active-Low Shutdown Input
FREQ	3	A	Frequency Adjust. An external resistor connected between this pin and Pin 6 (V_{DD}) sets the switching frequency of the LM2621.
FB	4	A	Output Voltage Feedback
SGND	5	GND	Signal Ground
V_{DD}	6	PWR	Power Supply for Internal Circuitry
BOOT	7	PWR	Bootstrap Supply for the Gate Drive of Internal MOSFET Power Switch
SW	8	PWR	Drain of the Internal MOSFET Power Switch

(1) I = Input, O = Output, PWR = Power, GND = Ground, A = Analog

6 Specifications

6.1 Absolute Maximum Ratings

See ⁽¹⁾⁽²⁾

	MIN	MAX	UNIT
SW Pin Voltage	-0.5	14.5	V
BOOT, V_{DD} , EN and FB Pins	-0.5	10	V
FREQ Pin		100	μ A
Power Dissipation ($T_A=25^\circ\text{C}$) ⁽³⁾		500	mW
T_{Jmax} ⁽³⁾		150	$^\circ\text{C}$
Lead Temp. (Soldering, 5 sec)		260	$^\circ\text{C}$
Storage temperature, T_{stg}	-65	150	$^\circ\text{C}$

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $P_{dmax} = (T_{Jmax} - T_A) / \theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower.

6.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
V _{DD}	2.5		5	V
FB	0		V _{DD}	V
EN	0		V _{DD}	V
BOOT	0		10	V
Ambient Temperature, T _A	-40		85	°C

6.3 Thermal Information

THERMAL METRIC ⁽¹⁾		LM2621	UNIT
		DGK (VSSOP)	
		8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance ⁽²⁾	160	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	52.7	°C/W
R _{θJB}	Junction-to-board thermal resistance	80.1	°C/W
ψ _{JT}	Junction-to-top characterization parameter	5.5	°C/W
ψ _{JB}	Junction-to-board characterization parameter	78.8	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

(2) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is P_{dmax} = (T_{jmax} - T_A) / θ_{JA} or the number given in the Absolute Maximum Ratings, whichever is lower.

6.4 Electrical Characteristics

 Unless otherwise specified: V_{DD} = V_{OUT} = 3.3 V, T_J = 25°C.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IN_ST}	Minimum Start-Up Supply Voltage ⁽¹⁾	I _{LOAD} = 0 mA	1.1		V
		I _{LOAD} = 0 mA, -40°C to 85°C		1.2	
V _{IN_OP}	Minimum Operating Supply Voltage (once started)	I _{LOAD} = 0 mA	0.65		V
V _{FB}	FB Pin Voltage		1.24		V
		-40°C to 85°C	1.2028	1.2772	
V _{OUT_MAX}	Maximum Output Voltage		14		V
V _{HYST}	Hysteresis Voltage ⁽²⁾		30		mV
		-40°C to 85°C		45	
η	Efficiency	V _{IN} = 3.6 V; V _{OUT} = 5 V; I _{LOAD} = 500 mA	87%		
		V _{IN} = 2.5 V; V _{OUT} = 3.3 V; I _{LOAD} = 200 mA	87%		
D	Switch Duty Cycle		70%		
		-40°C to 85°C	60%	80%	
I _{DD}	Operating Quiescent Current ⁽³⁾	FB Pin > 1.3 V; EN Pin at V _{DD}	80		μA
		FB Pin > 1.3 V; EN Pin at V _{DD} , -40°C to 85°C		110	
I _{SD}	Shutdown Quiescent Current ⁽⁴⁾	V _{DD} , BOOT and SW Pins at 5.0 V; EN Pin < 200 mV	0.01		μA
		V _{DD} , BOOT and SW Pins at 5.0 V; EN Pin < 200 mV, -40°C to 85°C		2.5	
I _{CL}	Switch Peak Current Limit		2.85		A

(1) Output in regulation, V_{OUT} = V_{OUT (NOMINAL)} ± 5%

(2) This is the hysteresis value of the internal comparator used for the gated-oscillator control scheme.

(3) This is the current into the V_{DD} pin.

(4) This is the total current into pins V_{DD}, BOOT, SW and FREQ.

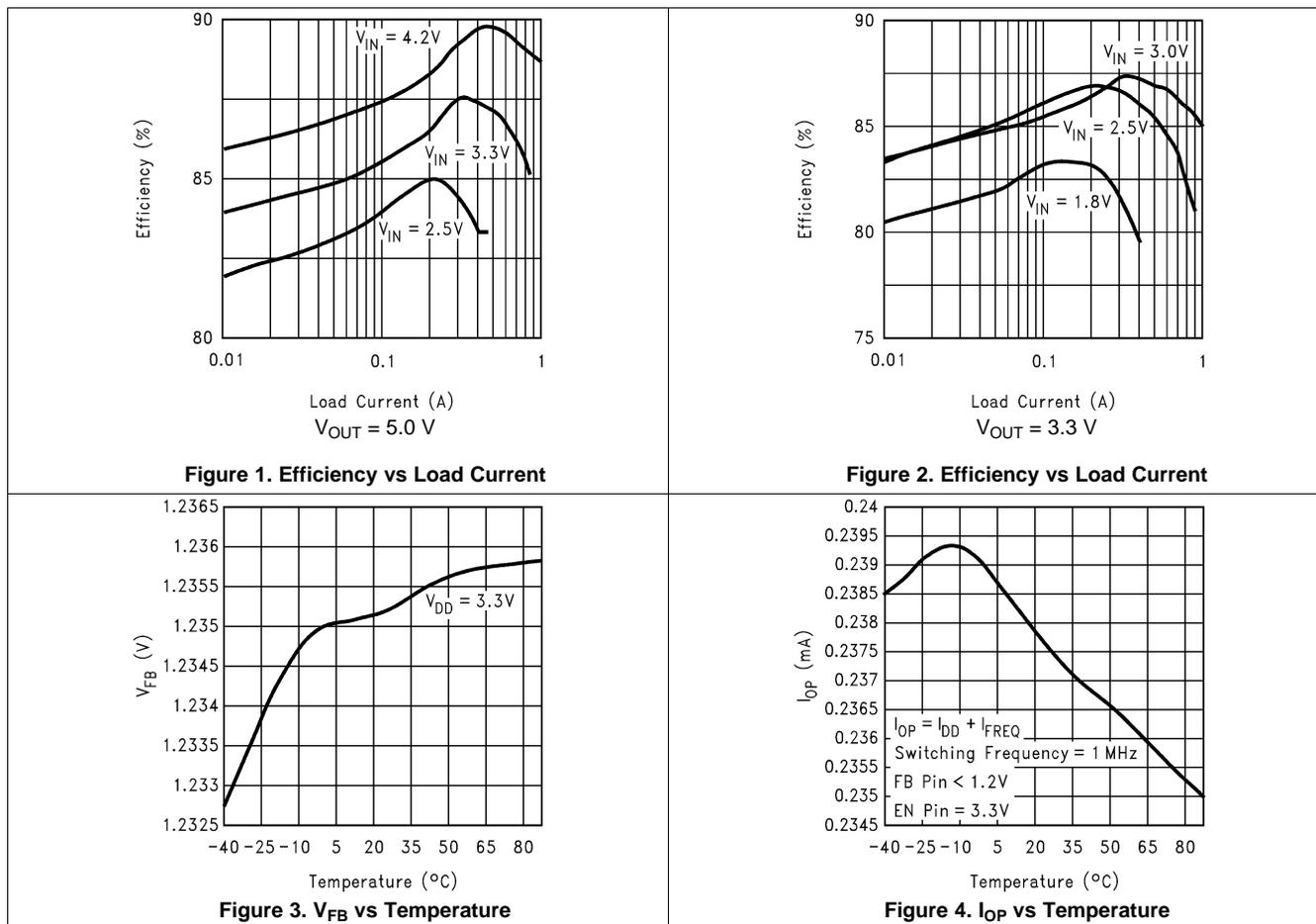
Electrical Characteristics (continued)

Unless otherwise specified: $V_{DD} = V_{OUT} = 3.3\text{ V}$, $T_J = 25^\circ\text{C}$.

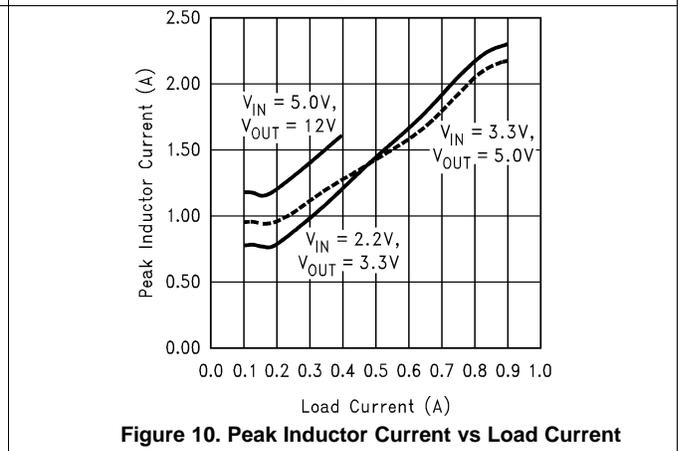
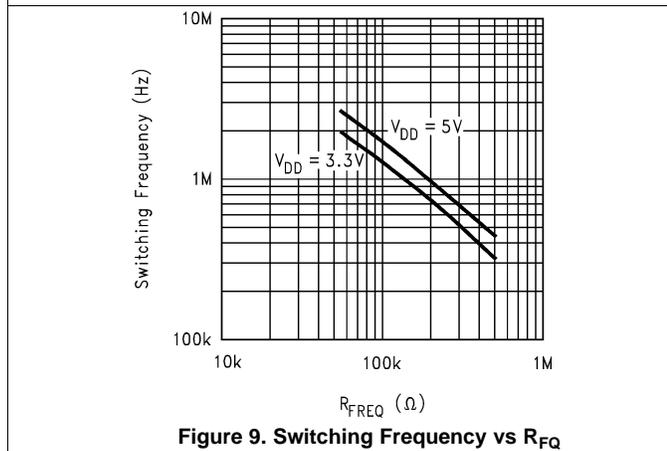
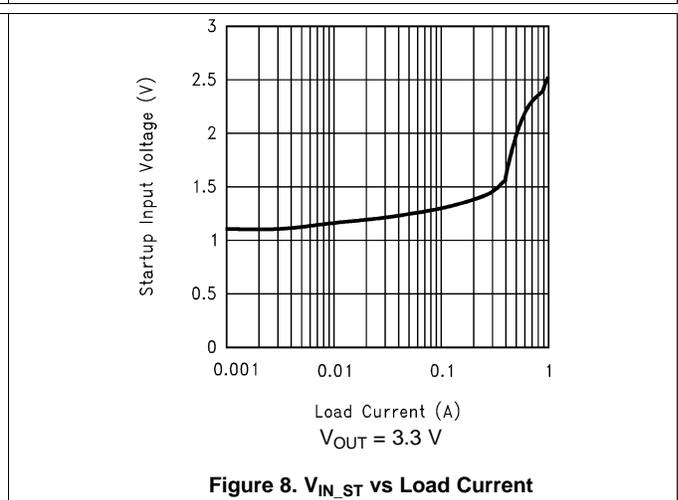
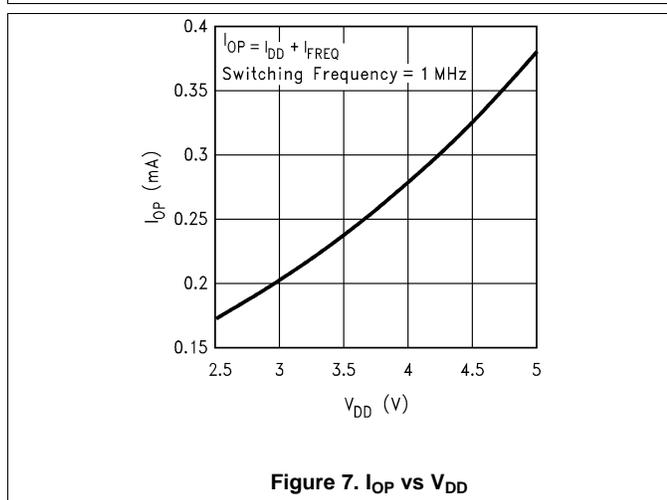
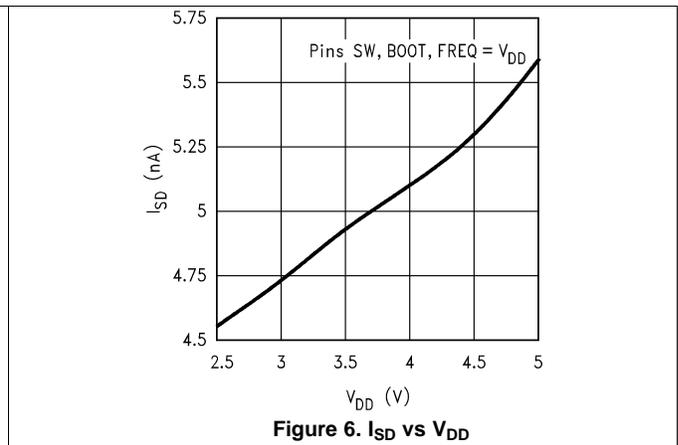
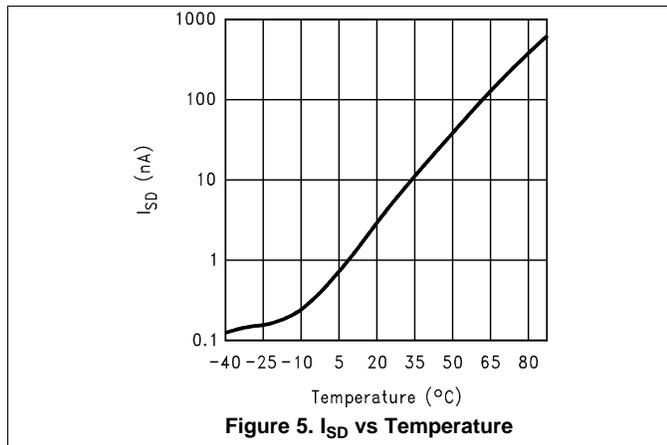
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
R_{DS_ON}	MOSFET Switch On Resistance		0.17		Ω	
ENABLE SECTION						
V_{EN_LO}	EN Pin Voltage Low ⁽⁵⁾	-40°C to 85°C			$0.15V_{DD}$	V
V_{EN_HI}	EN Pin Voltage High ⁽⁵⁾	-40°C to 85°C			$0.7V_{DD}$	V

(5) When the EN pin is below V_{EN_LO} , the regulator is shut down; when it is above V_{EN_HI} , the regulator is operating.

6.5 Typical Characteristics



Typical Characteristics (continued)



Typical Characteristics (continued)

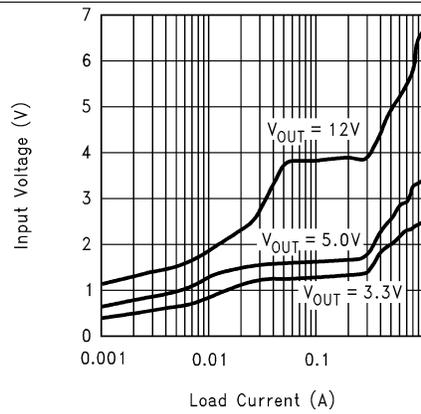


Figure 11. Maximum Load Current vs Input Voltage

7 Detailed Description

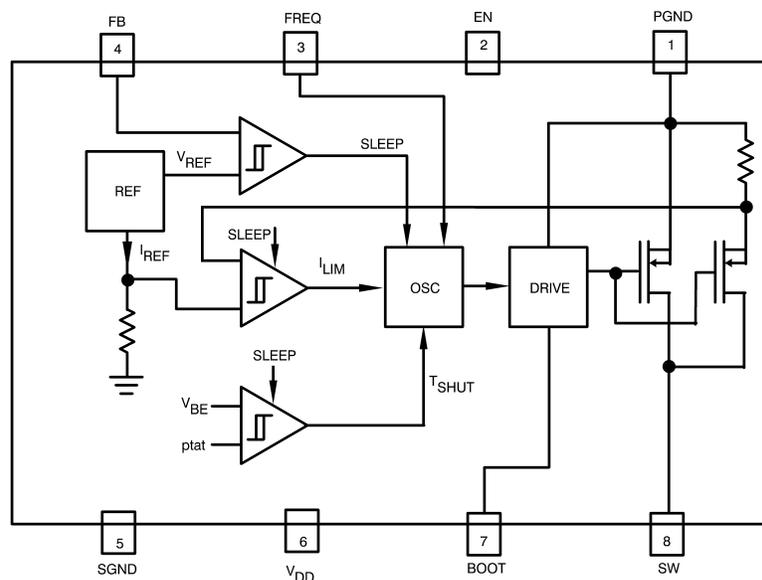
7.1 Overview

The LM2621 is designed to provide step-up DC-DC voltage regulation in battery-powered and low-input voltage systems. It combines a step-up switching regulator, N-channel power MOSFET, built-in current limit, thermal limit, and voltage reference in a single 8-pin VSSOP package [Pin Configuration and Functions](#). The switching DC-DC regulator boosts an input voltage between 1.2 V and 14 V to a regulated output voltage between 1.24 V and 14 V. The LM2621 starts from a low 1.1-V input and remains operational down to 0.65 V.

This device is optimized for use in cellular phones and other applications requiring a small size, low profile, as well as low quiescent current for maximum battery life during stand-by and shutdown. A high-efficiency gated-oscillator topology offers an output of up to 1 A.

Additional features include a built-in peak switch current limit, and thermal protection circuitry.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Gated Oscillator Control Scheme

A unique gated oscillator control scheme enables the LM2621 to have an ultra-low quiescent current and provides a high efficiency over a wide load range. The switching frequency of the internal oscillator is programmable using an external resistor and can be set between 300 kHz and 2 MHz.

This control scheme uses a hysteresis window to regulate the output voltage. When the output voltage is below the upper threshold of the window, the LM2621 switches continuously with a fixed duty cycle of 70% at the switching frequency selected by the user. During the first part of each switching cycle, the internal N-channel MOSFET switch is turned on. This causes the current to ramp up in the inductor and store energy. During the second part of each switching cycle, the MOSFET is turned off. The voltage across the inductor reverses and forces current through the diode to the output filter capacitor and the load. Thus when the LM2621 switches continuously, the output voltage starts to ramp up. When the output voltage hits the upper threshold of the window, the LM2621 stops switching completely. This causes the output voltage to droop because the energy stored in the output capacitor is depleted by the load. When the output voltage hits the lower threshold of the hysteresis window, the LM2621 starts switching continuously again causing the output voltage to ramp up towards the upper threshold. [Figure 12](#) shows the switch voltage and output voltage waveforms.

Because of this type of control scheme, the quiescent current is inherently very low. At light loads the gated oscillator control scheme offers a much higher efficiency compared to the conventional PWM control scheme.

Feature Description (continued)

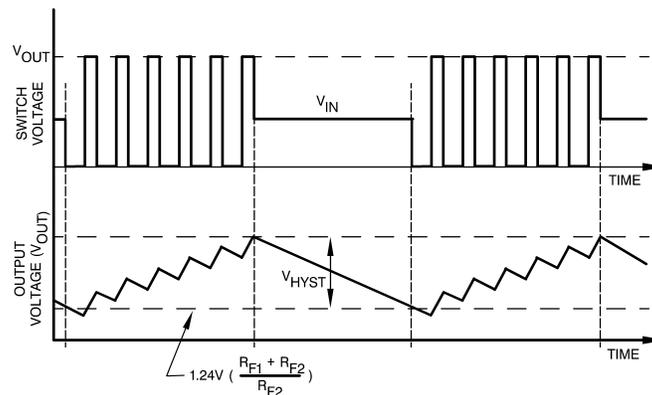


Figure 12. Typical Step-Up Regulator Waveforms

7.3.2 Low Voltage Start-Up

The LM2621 can start-up from input voltages as low as 1.1 V. On start-up, the control circuitry switches the N-channel MOSFET continuously at 70% duty cycle until the output voltage reaches 2.5 V. After this output voltage is reached, the normal step-up regulator feedback and gated oscillator control scheme take over. Once the device is in regulation it can operate down to a 0.65-V input, since the internal power for the IC can be bootstrapped from the output using the V_{DD} pin.

7.3.3 Output Voltage Ripple Frequency

A major component of the output voltage ripple is due to the hysteresis used in the gated oscillator control scheme. The frequency of this voltage ripple is proportional to the load current. The frequency of this ripple does not necessitate the use of larger inductors and capacitors however, since the size of these components is determined by the switching frequency of the oscillator which can be set up to 2 MHz using an external resistor.

7.3.4 Internal Current Limit and Thermal Protection

An internal cycle-by-cycle current limit serves as a protection feature. This is set high enough (2.85 A typical, approximately 4 A maximum) so as not to come into effect during normal operating conditions. An internal thermal protection circuitry disables the MOSFET power switch when the junction temperature (T_J) exceeds about 160°C. The switch is re-enabled when T_J drops below approximately 135°C.

7.4 Device Functional Modes

7.4.1 Shutdown

The LM2621 features a shutdown mode that reduces the quiescent current to less than a specified 2.5- μ A overtemperature. This extends the life of the battery in battery powered applications. During shutdown, all feedback and control circuitry is turned off. The regulator's output voltage drops to one diode drop below the input voltage. Entry into the shutdown mode is controlled by the active-low logic input pin EN (Pin 2). When the logic input to this pin pulled below 0.15 V_{DD} , the device goes into shutdown mode. The logic input to this pin should be above 0.7 V_{DD} for the device to work in normal step-up mode.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM2621 is primarily used as a Boost type step-up converter. The following section provides information regarding connection and component choices to build a successful boost converter. Examples of typical applications are also provided including a SEPIC step-up/step-down topology. More details on designing a SEPIC converter can be found here: [SLYT309](#).

8.2 Typical Applications

8.2.1 Step-Up DC-DC Converter Typical Application Using LM2621

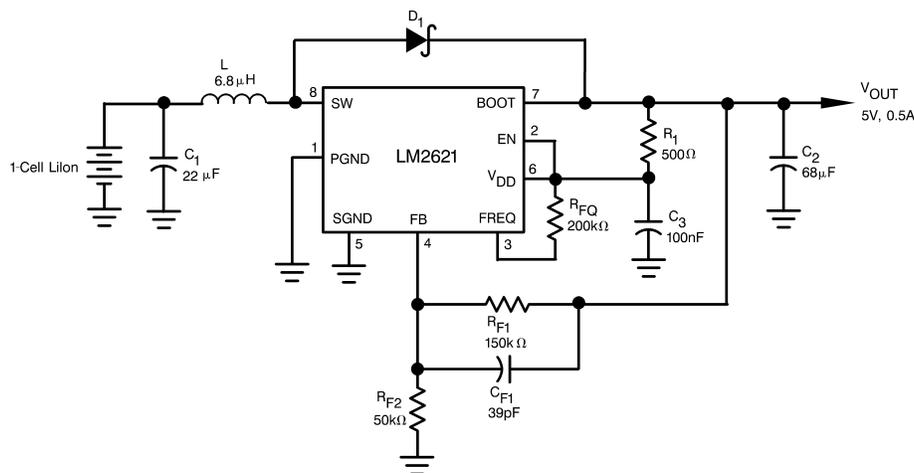


Figure 13. Typical Circuit

8.2.1.1 Design Requirements

In order to successfully build an application, the designer should have the following parameters:

- Output voltage to set the feedback voltage divider and to assess the source for biasing the V_{DD} pin.
- Input voltage range (min and max) to ensure safe operation within absolute max. rating of the IC.
- Output current to ensure that the system will not hit the internal peak current limit of the IC (2.85 A typical) during normal operation.

8.2.1.2 Detailed Design Procedure

8.2.1.2.1 Setting the Output Voltage

The output voltage of the step-up regulator can be set between 1.24 V and 14 V by connecting a feedback resistive divider made of R_{F1} and R_{F2} . The resistor values are selected as follows:

$$R_{F2} = R_{F1} / [(V_{OUT} / 1.24) - 1] \quad (1)$$

A value of 150 kΩ is suggested for R_{F1} . Then, R_{F2} can be selected using the above equation. A 39-pF capacitor (C_{F1}) connected across R_{F1} helps in feeding back most of the AC ripple at V_{OUT} to the FB pin. This helps reduce the peak-to-peak output voltage ripple as well as improve the efficiency of the step-up regulator, because a set hysteresis of 30 mV at the FB pin is used for the gated oscillator control scheme.

Typical Applications (continued)

8.2.1.2.2 Bootstrapping

When the output voltage (V_{OUT}) is between 2.5 V and 5.0 V a bootstrapped operation is suggested. This is achieved by connecting the V_{DD} pin (Pin 6) to V_{OUT} . However if the V_{OUT} is outside this range, the V_{DD} pin should be connected to a voltage source whose range is between 2.5 V and 5 V. This can be the input voltage (V_{IN}), V_{OUT} stepped down using a linear regulator, or a different voltage source available in the system. This is referred to as non-bootstrapped operation. The maximum acceptable voltage at the BOOT pin (Pin 7) is 10 V.

8.2.1.2.3 Setting the Switching Frequency

The switching frequency of the oscillator is selected by choosing an external resistor (R_{FQ}) connected between $FREQ$ and V_{DD} pins. See [Figure 9](#) for choosing the R_{FQ} value to achieve the desired switching frequency. A high switching frequency allows the use of very small surface mount inductors and capacitors and results in a very small solution size. A switching frequency between 300 kHz and 2 MHz is recommended.

8.2.1.2.4 Inductor Selection

The LM2621's high switching frequency enables the use of a small surface mount inductor. A 6.8- μ H shielded inductor is suggested. The inductor should have a saturation current rating higher than the peak current it will experience during circuit operation (see [Figure 10](#)). Less than 100-m Ω ESR is suggested for high efficiency.

Open-core inductors cause flux linkage with circuit components and interfere with the normal operation of the circuit. They should be avoided. For high efficiency, choose an inductor with a high frequency core material, such as ferrite, to reduce the core losses. To minimize radiated noise, use a toroid, pot core or shielded core inductor. The inductor should be connected to the SW pin as close to the IC as possible. See [Table 1](#) for a list of the inductor manufacturers.

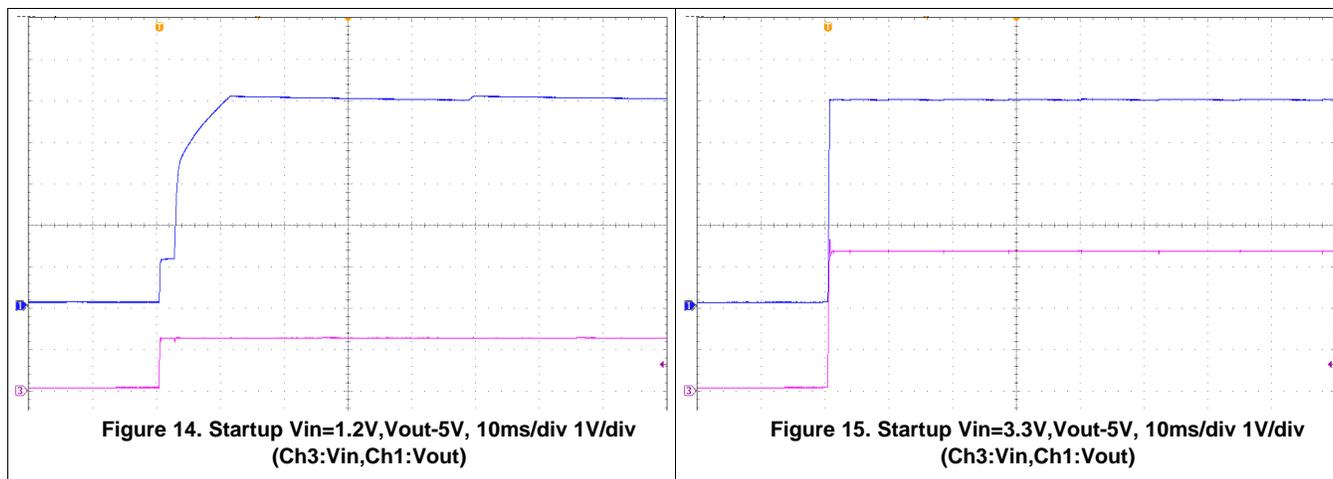
8.2.1.2.5 Output Diode Selection

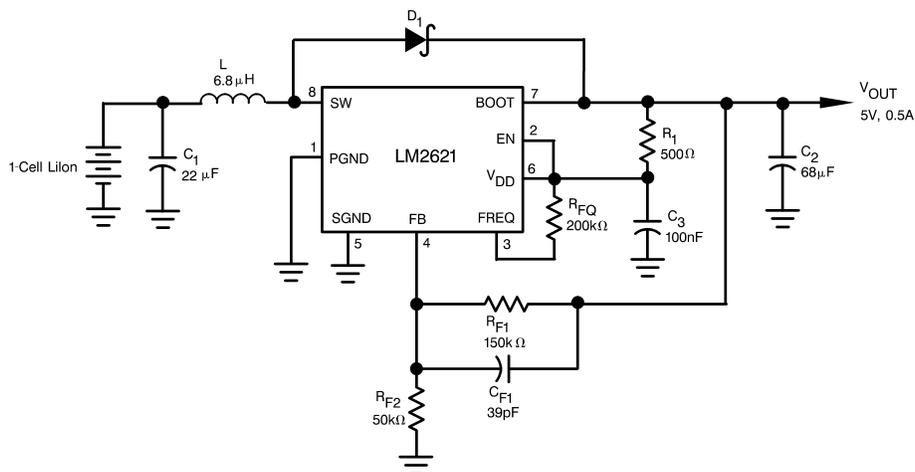
A Schottky diode should be used for the output diode. The forward current rating of the diode should be higher than the load current, and the reverse voltage rating must be higher than the output voltage. Do not use ordinary rectifier diodes, since slow switching speeds and long recovery times cause the efficiency and the load regulation to suffer. [Table 1](#) shows a list of the diode manufacturers.

8.2.1.2.6 Input and Output Filter Capacitors Selection

Tantalum chip capacitors are recommended for the input and output filter capacitors. A 22- μ F capacitor is suggested for the input filter capacitor. It should have a DC working voltage rating higher than the maximum input voltage. A 68- μ F tantalum capacitor is suggested for the output capacitor. The DC working voltage rating should be greater than the output voltage. Very high ESR values ($> 3\Omega$) should be avoided.

8.2.1.3 Application Curves



Typical Applications (continued)
8.2.2 5-V / 0.5-A Step-Up Regulator

Figure 16. 5-V/0.5A Step-Up Regulator
8.2.2.1 Design Requirements

Design requirement is the same to the typical application shown earlier. Components have been chosen that comply with the required maximum height. See [Design Requirements](#) for the design requirement and following sections for the detailed design procedure.

8.2.2.2 Detailed Design Procedure

Follow the detailed design procedure in [Detailed Design Procedure](#).

Typical Applications (continued)

Table 1. Bill of Materials

	Manufacturer	Part Number
U1	TI	LM2621MM
C1	Vishay/Sprague	595D226X06R3B2T, Tantalum
C2	Vishay/Sprague	595D686X0010C2T, Tantalum
D1	Motorola	MBRS140T3
L	Coilcraft	DT1608C-682

8.2.3 2-mm Tall 5-V / 0.2-A Step-Up Regulator for Low Profile Applications

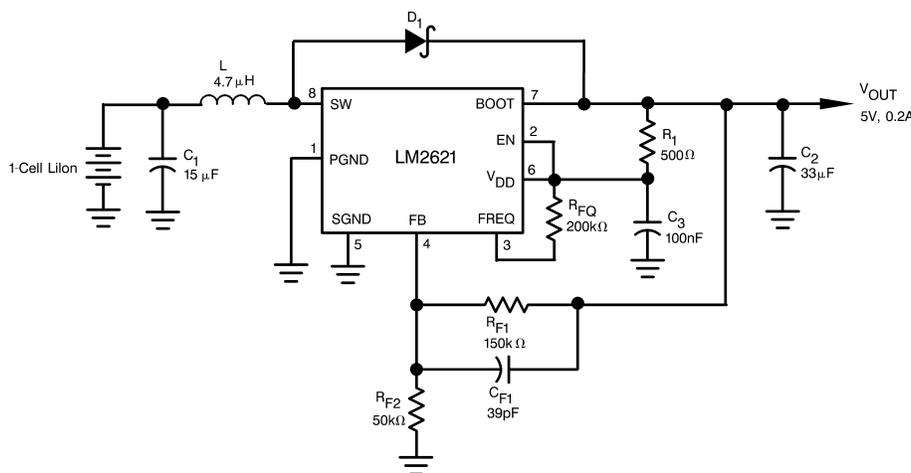


Figure 17. 2-mm Tall 5-V/0.2A Step-Up Regulator for Low Profile Applications

8.2.3.1 Design Requirements

Design requirement is the same to the typical application shown earlier. Components have been chosen that comply with the required maximum height. See [Design Requirements](#) for the design requirement and following sections for the detailed design procedure.

8.2.3.2 Detailed Design Procedure

Follow the detailed design procedure in [Detailed Design Procedure](#).

Table 2. Bill of Materials

	Manufacturer	Part Number
U1	TI	LM2621MM
C1	Vishay/Sprague	592D156X06R3B2T, Tantalum
C2	Vishay/Sprague	592D336X06R3C2T, Tantalum
D1	Motorola	MBRS140T3
L	Vishay/Dale	ILS-3825-03

8.2.4 3.3-V / 0.5-A SEPIC Regulator

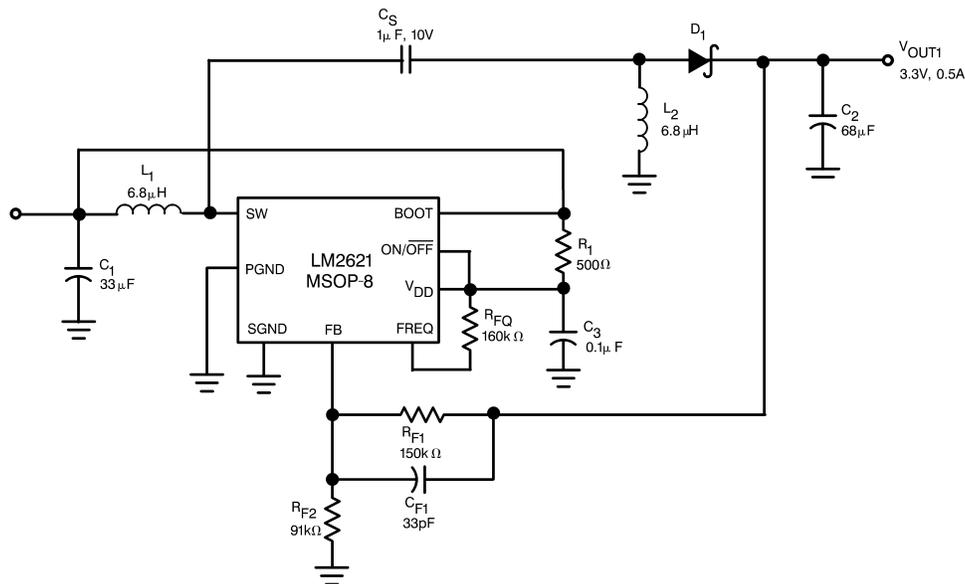


Figure 18. 3.3-V/0.5-A SEPIC Regulator

8.2.4.1 Design Requirements

Design requirement for the SEPIC is similar to that of a boost but the current flowing through the switch is the addition of the current flowing through L1 and L2. As a result, the peak current through the main switch is $I_{IN} + I_{OUT} + 0.5 \times \Delta I_{L1} + 0.5 \times \Delta I_{L2}$. See [SLYT309](#) for detail on the specific design requirement of a SEPIC converter.

8.2.4.2 Detailed Design Procedure

Follow the detailed design procedure in [Detailed Design Procedure](#).

Table 3. Bill of Materials

	Manufacturer	Part Number	Description
U1	TI	LM2621MM	Low Input Voltage Regulator
C1	Sanyo	10CV220AX, SMT AL-Electrolytic	220 μF
C2	TDK	C2012X7R1C225M, MLCC	2.2 μF
C3	Vishay	VJ0603A331KXXAT	33 pF
C4	TDK	C3225X7R0J107MT	100 μF
C5, C6	Vishay	VJ0603Y104KXXAT	0.1 μF
D1	Philips	BAT54C	VR = 1V
D2	Vishay	MBRS120	1A / VR = 20V
L1, L2	Coilcraft	DO1813P-682HC	6.8 μH
R1	Vishay	CRCW08054990FRT6	499 Ω
R2	Vishay	CRCW08051503FRT6	150 kΩ
R3	Vishay	CRCW08053923FRT6	392 kΩ
R4	Vishay	CRCW08059092FRT6	90.9 kΩ

9 Power Supply Recommendations

The power line feeding the LM2621 should have low impedance. The input capacitor of the system should be placed as close to VIN as possible. If the power supply is very noisy, an additional bulk capacitor might be necessary in the system to ensure that clean power is delivered to the IC.

10 Layout

10.1 Layout Guidelines

High switching frequencies and high peak currents make a proper layout of the PC board an important part of design. Poor design can cause excessive EMI and ground-bounce, both of which can cause malfunction and loss of regulation by corrupting voltage feedback signal and injecting noise into the control section.

Power components - such as the inductor, input and output filter capacitors, and output diode - should be placed as close to the regulator IC as possible, and their traces should be kept short, direct and wide. The ground pins of the input and output filter capacitors and the PGND and SGND pins of LM2621 should be connected using short, direct and wide traces. The voltage feedback network (R_{F1} , R_{F2} , and C_{F1}) should be kept very close to the FB pin. Noisy traces, such as from the SW pin, should be kept away from the FB and V_{DD} pins. The traces that run between V_{out} and the FB pin of the IC should be kept away from the inductor flux. Always provide sufficient copper area to dissipate the heat due to power loss in the circuitry and prevent the thermal protection circuitry in the IC from shutting the IC down.

10.2 Layout Example

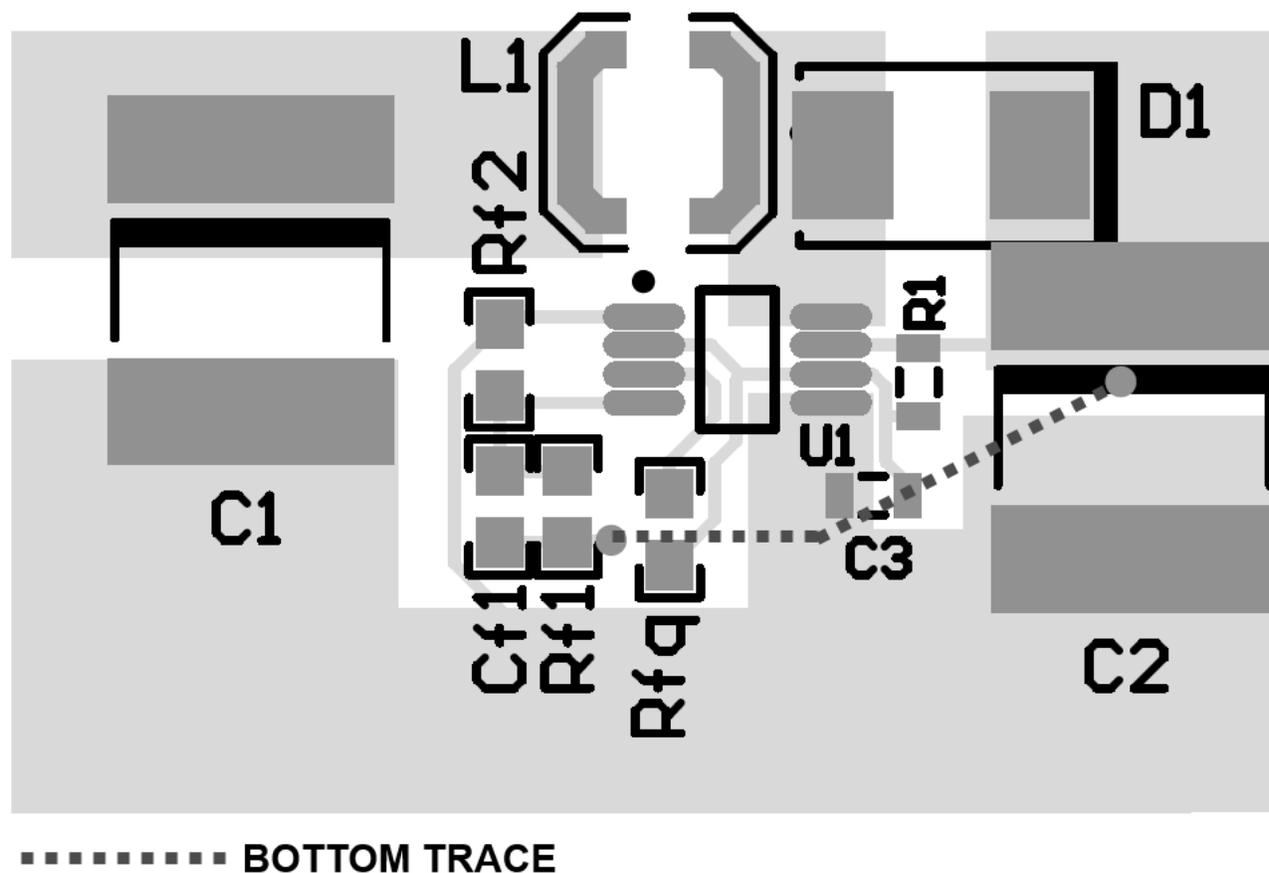


Figure 19. LM2621 PCB Layout

11 Device and Documentation Support

11.1 Device Support

11.1.1 Third-Party Products Disclaimer

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11.2 Documentation Support

11.2.1 Related Documentation

For related documentation, see the following:

- *Designing DC/DC converters based on SEPIC topology*, [SLYT309](#)

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](#), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM2621MM/NOPB	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	S06A
LM2621MM/NOPB.A	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	S06A
LM2621MM/NOPB.B	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	S06A
LM2621MMX/NOPB	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	S06A
LM2621MMX/NOPB.A	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	S06A
LM2621MMX/NOPB.B	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	S06A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

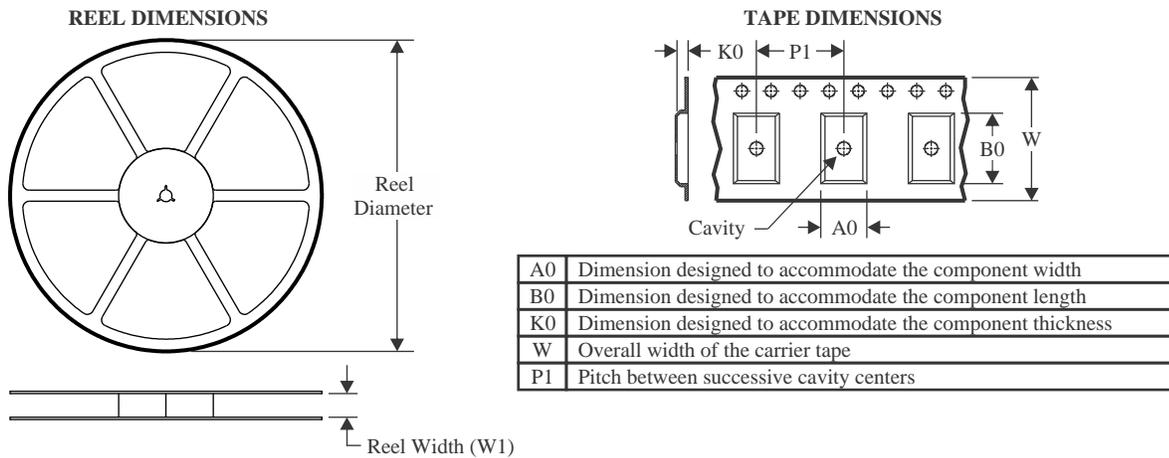
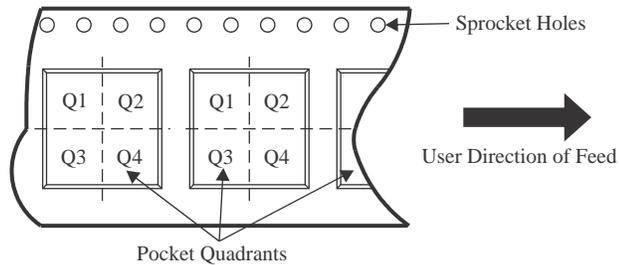
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

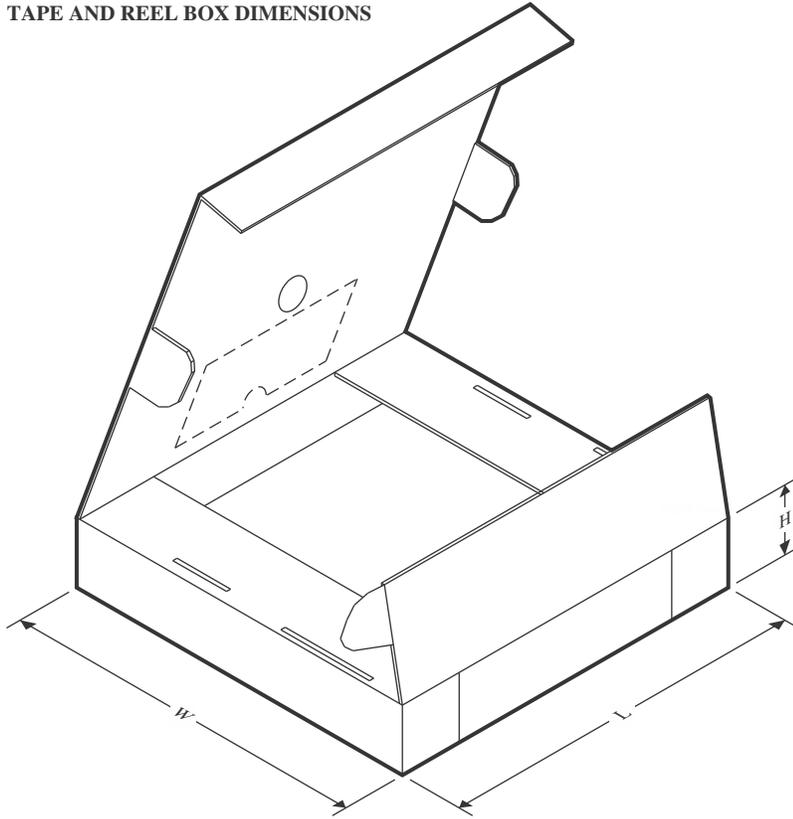
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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2621MM/NOPB	VSSOP	DGK	8	1000	177.8	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM2621MMX/NOPB	VSSOP	DGK	8	3500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2621MM/NOPB	VSSOP	DGK	8	1000	210.0	185.0	35.0
LM2621MMX/NOPB	VSSOP	DGK	8	3500	367.0	367.0	35.0

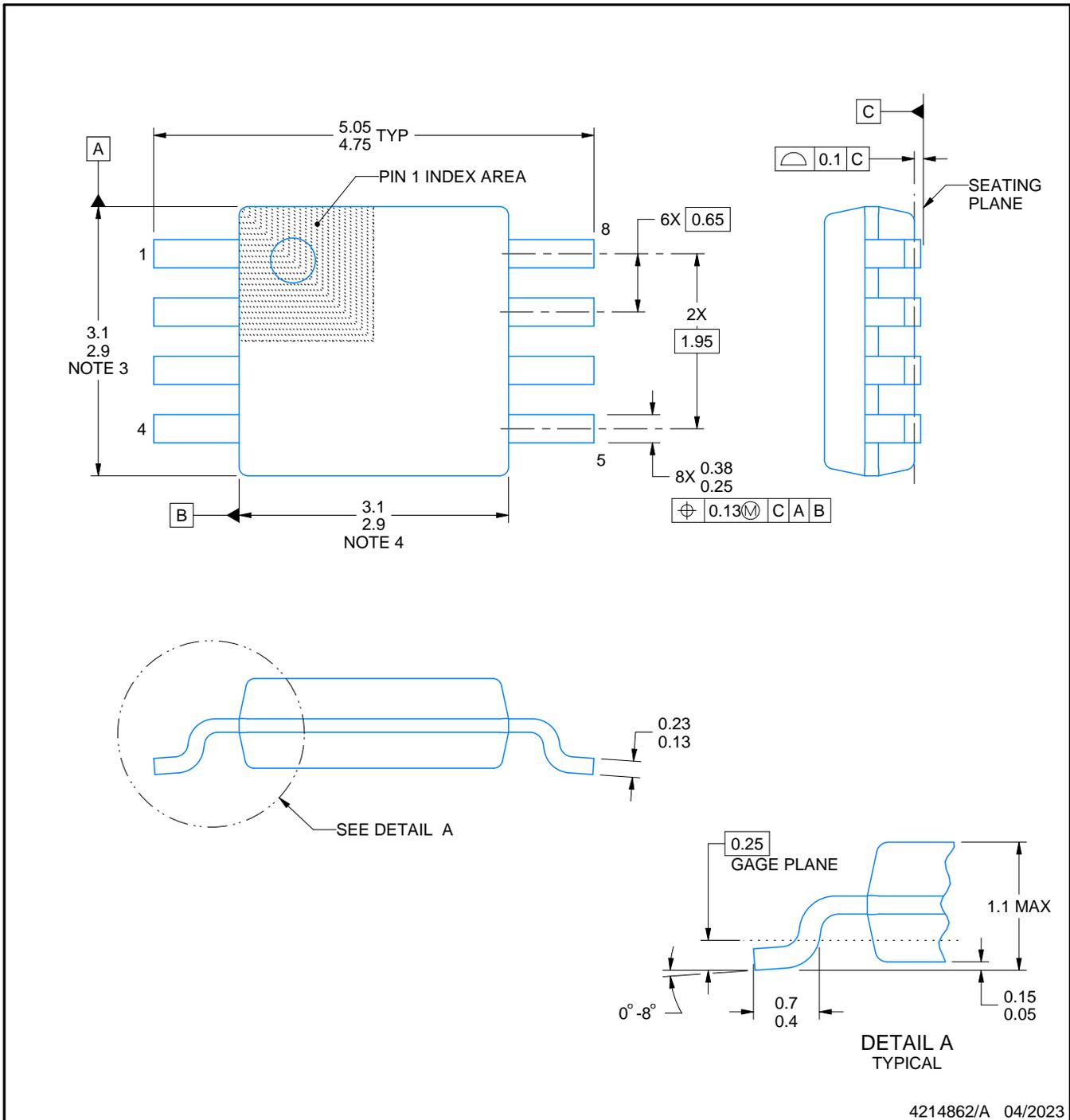
DGK0008A



PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



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NOTES:

PowerPAD is a trademark of Texas Instruments.

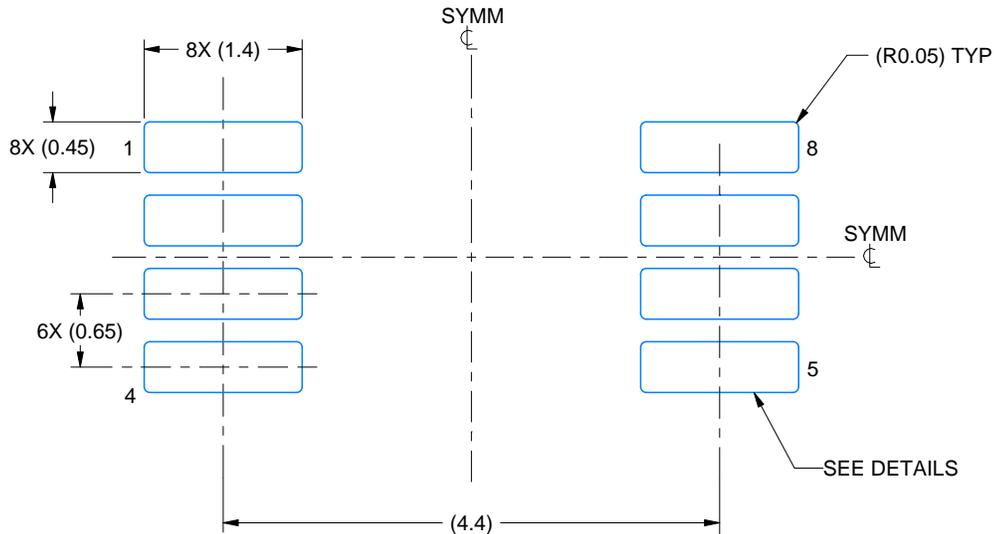
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

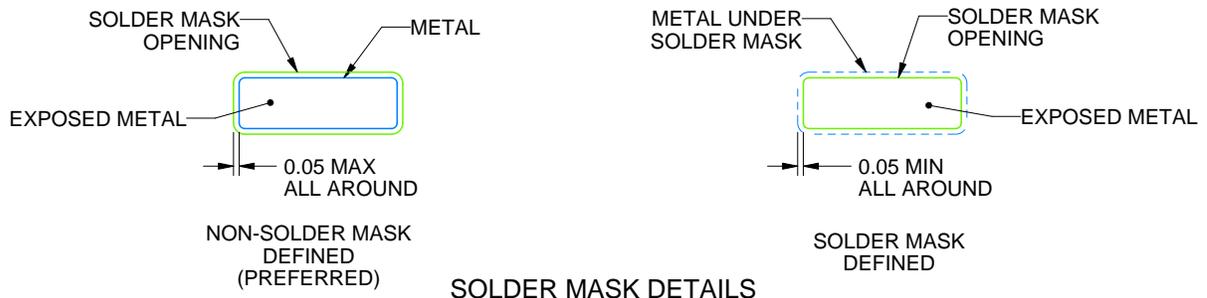
DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



SOLDER MASK DETAILS

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NOTES: (continued)

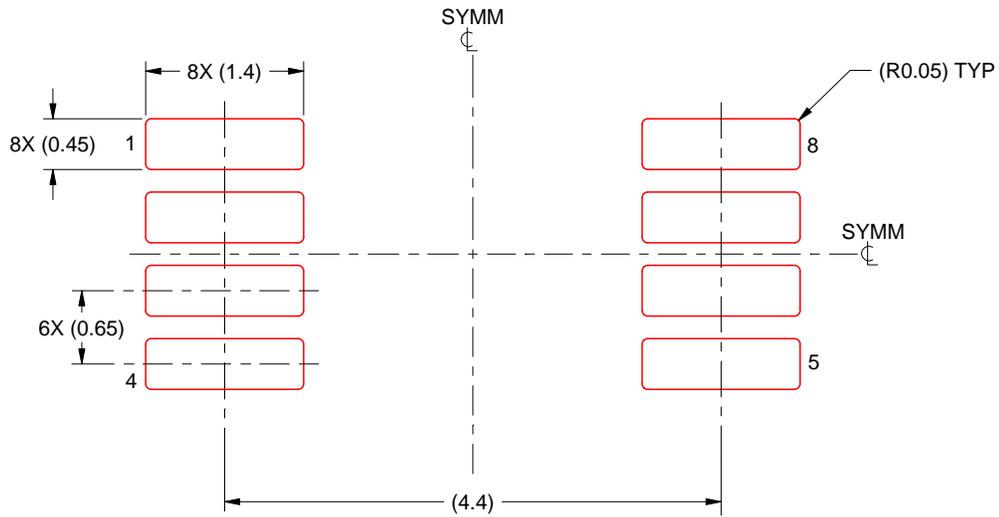
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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